



## Schedule of Scope to Certificate of Approval Independent Testing Laboratory

IECQ Certificate No.: IECQ-L DEKRA 16.0002

CB Certificate No.: DEKRA-T5A-003

Schedule Number: IECQ-L DEKRA 16.0002-S    Rev No.: 3    Rev. Date: 2019/08/19    Page 1 of 1

### 1. Environmental and Reliability Testing of Electronic Components, Assemblies, and Related Materials

| Description test  | Standard   | Remarks                    |
|---|--|----------------------------|
| Consumer / Commercial / Industrial (JESD 47) and Automotive / Military accelerated environment reliability stress tests.<br><br>(Including: Pre-condition / MSL / Accelerated Temperature-Humidity test / Unbiased Autoclave /Liquid to liquid thermal shock/Air to air thermal shock/ Unbiased HAST/biased HAST/Temperature-Humidity with bias test / Temperature Cycling test / Power and temperature cycling / High and low Temperature storage test / IOL/ Salt)  | J-STD-020, JESD22-A101/A102/A103/A104/A105/A106/A107/A110/A113/A118/A119; IEC-60068-2-1/2/3/14/38/52/,<br><br>MIL-STD-202/750/810/883, JESD JEP001; EIA-364-32, EIAJ ED-4701, AEC-Q200-004; AEC-Q005/Q006, JESD22-A105   | Or customer specified test |
| Consumer/ Commercial / Industrial (JESD 47) and Automotive / Military accelerated lifetime simulation tests.<br><br>(Including: Temperature, Bias, and Operating Life test / early life failure rate / Endurance and Data retention test / Short circuit / Low Temperature Operating Life / Miscellaneous test)   | JESD22-A101/A108/A117,<br>MIL-STD-202/750/810/883,<br>AEC-Q100-005/006/008/012,<br>AEC-Q101-004/006,<br>Customer standards   | Or customer specified test |
| Consumer / Commercial / Industrial (JESD 47) and Automotive / Military 2nd level integration platform service.<br><br>(Including : Pre-SMT/SMT / Temperature Cycling test / Temperature-Humidity test / Drop / Shock / Bending(9point) / Pull and Push test / Solderability / Press / Shear / Hardness / RCA / Durability / Peeling / Terminal Strength / Resistance to Solvents / Resistance to Solder Heat / Hermeticity / Package Warpage Measurement of Surface-Mount Integrated Circuits at Elevated Temperature / Printed Wiring Board Strain Gage Test / Mechanical Compressive Static Stress Test | IPC-7525/9701/9702/9704/9707/9708/A-610, JESD22-A101/A104/A106/A109/A111/B100/B102/B103/B104/B105/B106/B107/B108/B110/B111/B112/B113/B115/B116/B117/B119; EIAJ ED-4702,<br><br>EIA-364-09/13; AEC-Q100-001/010; AEC-Q101-003, AEC-Q200-003/005/ 006; MIL-STD-202/750/810/883,<br>J-STD-002/003; ASTM D3363,<br>ASTM F2357; SEMI G86-0303,<br>IEC 60068-2-21; IEC-60068-2-14; IPC-TM-650, | Or customer specified test |
| Electrical Analysis, Sample Preparation (Decap, X-section, etc), NDE (Non-destructive Engineering), Physical & Chemical Analysis (Including Hazardous Substances) and IC package.   | IPC-TM-650,<br>IPC-610,<br>J-STD-020,<br>JESD201,<br>EIA-469, IEC62321, EN14582,   | Or customer specified test |

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